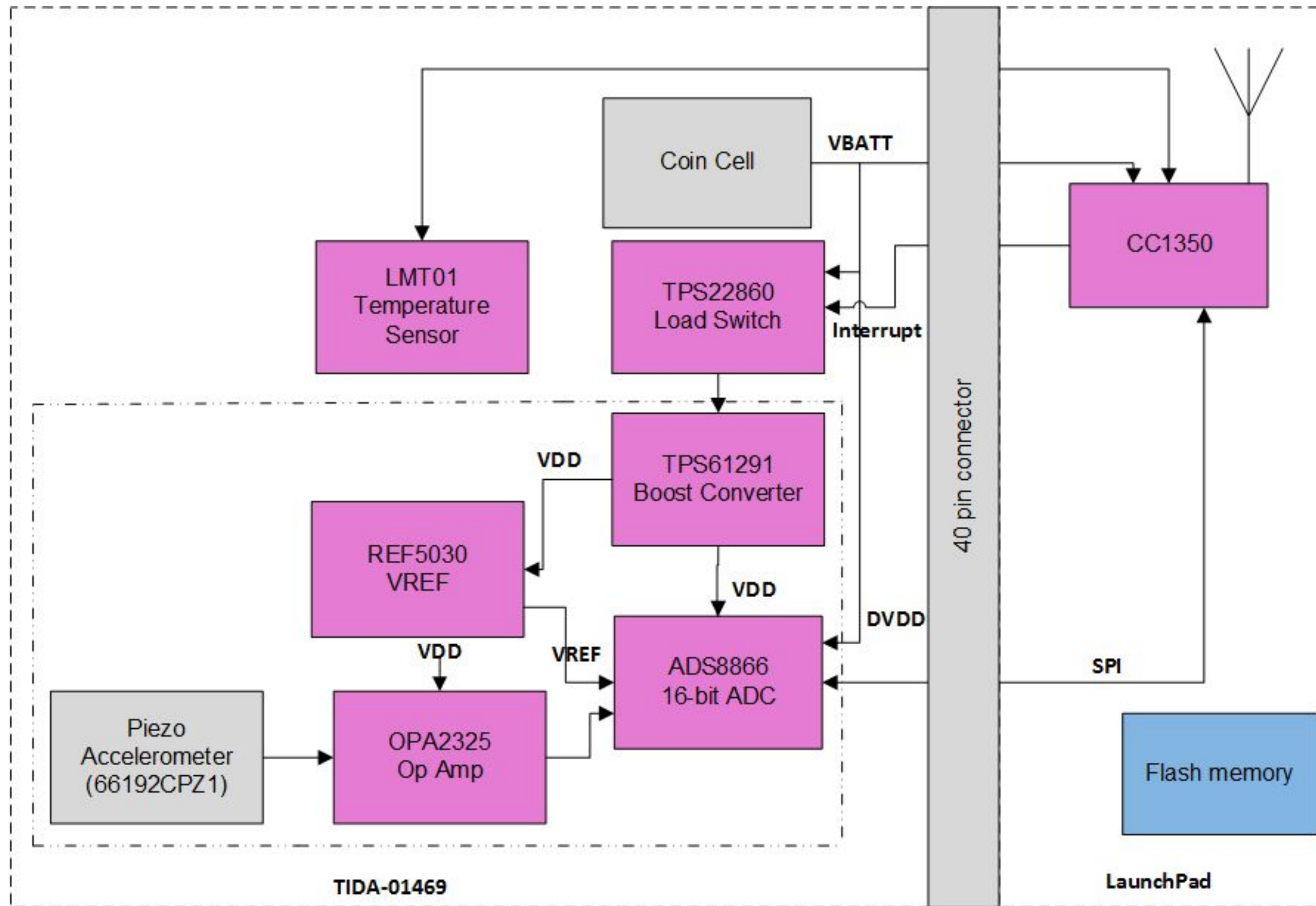
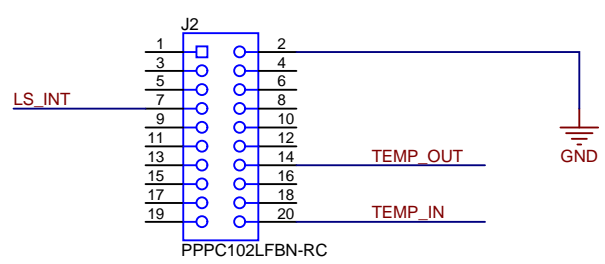
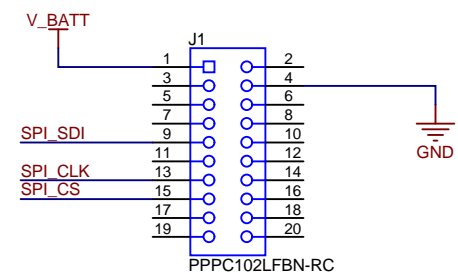


| Revision History |       |               |             |       |
|------------------|-------|---------------|-------------|-------|
| Rev              | ECN # | Approved Date | Approved by | Notes |
| N/A              | N/A   | N/A           | N/A         | N/A   |



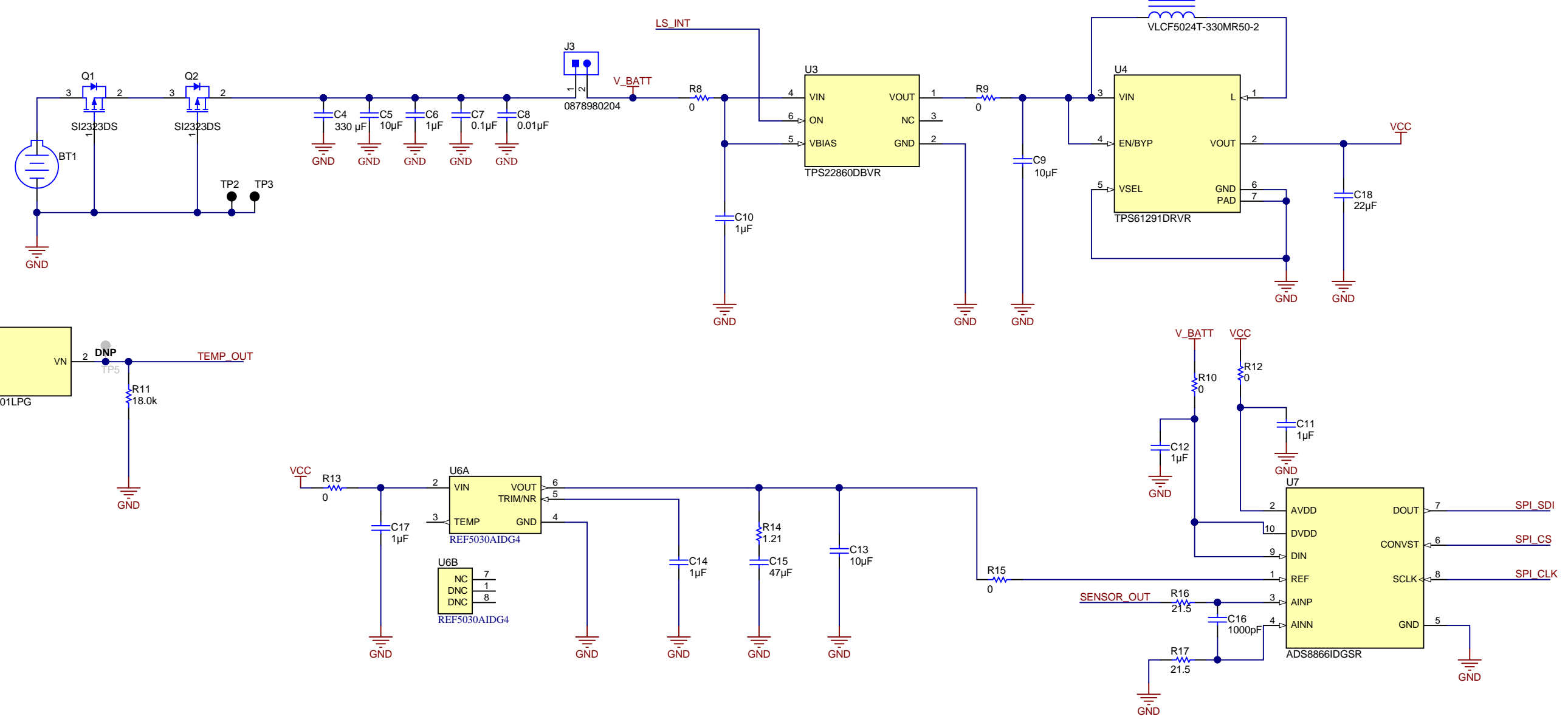
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| Number: <a href="#">TIDA-01469</a>                | Rev: <a href="#">E1</a>   | Assembly Variant: <a href="#">001</a>                                      | Sheet: <a href="#">1 of 4</a>                     |
| SVN Rev: <a href="#">Version control disabled</a> | File: <a href="#">TIDA-01469_CoverSheet.SchDoc</a>                              | Size: <a href="#">B</a>  | <a href="http://www.ti.com">http://www.ti.com</a> |
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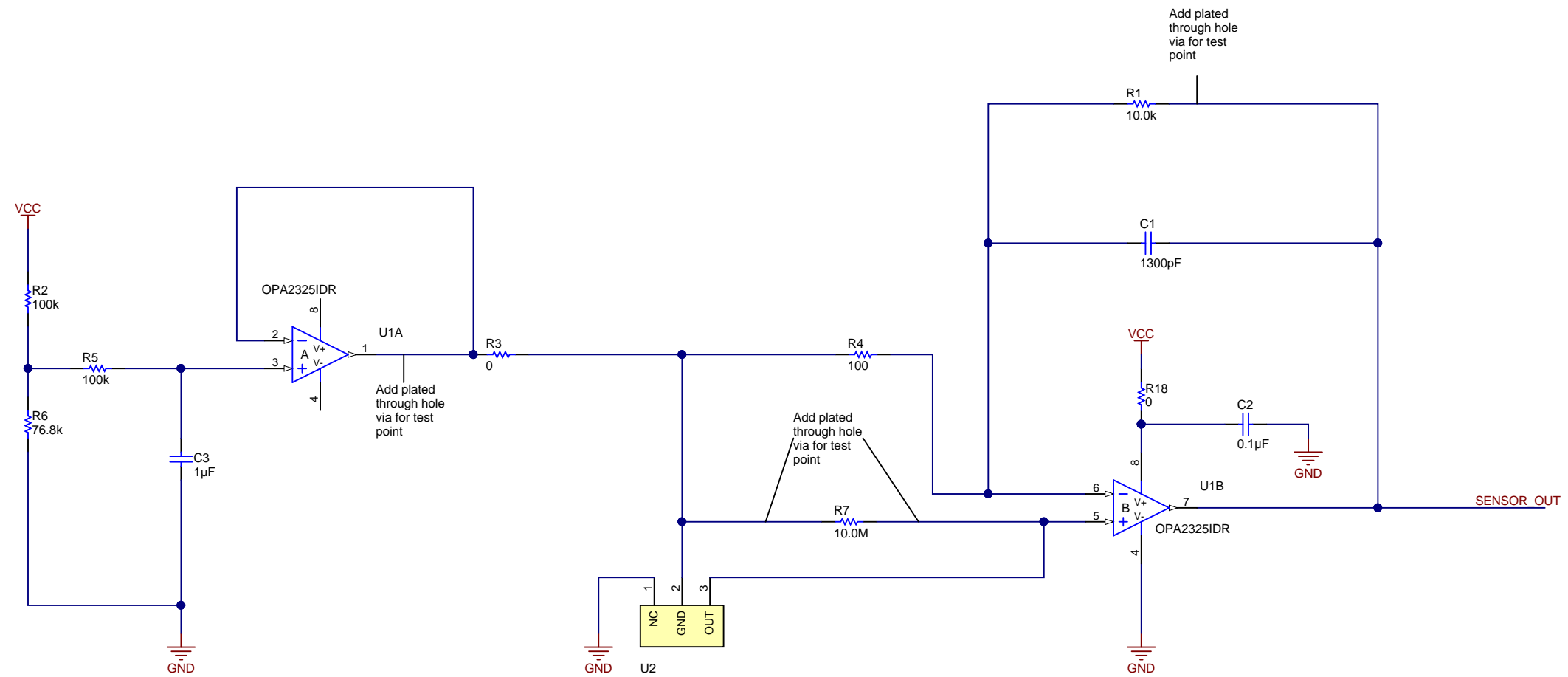
Pin assignments when used with CC1350 LaunchPad (LAUNCHXL-CC1350):

|       |          |
|-------|----------|
| DIO08 | TEMP_OUT |
| DIO10 | SPL_CLK  |
| DIO15 | TEMP_IN  |
| DIO19 | LS_INT   |
| DIO21 | SPI_CS   |
| DIO22 | SPI_SDI  |



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| TID #: TIDA-01469                    | Project Title: Motor Monitoring Using Wireless Vibration Sensor | Sheet Title: Main  |                          |
| Number: TIDA-01469                   | Rev: E1   | Assembly Variant: 001  | Sheet: 2 of 4            |
| SVN Rev: Version control disabled    | File: TIDA-01469_Main.SchDoc                                    | Size: B  | http://www.ti.com        |
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| TID #: TIDA-01469                       | Project Title: <a href="#">Motor Monitoring Using Wireless Vibration Sensor</a> | Sheet: 3 of 4  |   |
| Number: TIDA-01469                      | Rev: E1   | Sheet Title: <a href="#">Piezo Sensor</a>                                  | <a href="http://www.ti.com">http://www.ti.com</a><br>© Texas Instruments 2017 |
| SVN Rev: Version control disabled       | Assembly Variant: 001   | Size: B  |   |
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PCB Number: TIDA-01469  
PCB Rev: E1

PCB LOGO  
Texas Instruments

PCB LOGO  
Pb-Free Symbol

PCB LOGO  
FCC disclaimer




LBL1  
PCB Label  
Size: 0.65" x 0.20"

ZZ1  
Label Assembly Note  
This Assembly Note is for PCB labels only

ZZ2  
Assembly Note  
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3  
Assembly Note  
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4  
Assembly Note  
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

|   |   |   |  |
|---|---|---|--|
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| TID #: <a href="#">TIDA-01469</a>                 | Project Title: <a href="#">Motor Monitoring Using Wireless Vibration Sensor</a> |   |  |
| Number: <a href="#">TIDA-01469</a>                | Rev: <a href="#">E1</a>   | Sheet Title: <a href="#">Hardware</a>         |  |
| SVN Rev: <a href="#">Version control disabled</a> | Assembly Variant: <a href="#">001</a>   | Sheet: <a href="#">4</a> of <a href="#">4</a> |  |
| Drawn By: <a href="#">Nathan Siegel</a>           | File: <a href="#">TIDA-01469_EVM_Hardware.SchDoc</a>                            | Size: <a href="#">B</a>                       |  |
| Engineer: <a href="#">Nathan Siegel</a>           | Contact: <a href="http://www.ti.com/support">http://www.ti.com/support</a>      |   |  |

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